

## **REMARKS**

Claims 2, 3, 5 and 6 are amended to refer to the layer of thermally conducting material recited in claim 11 rather than the heat shield mentioned in former claim 1. Basis for these amendments is found, *inter alia*, in Figure 1 and the related description at Paragraphs 37-42 of the description, which clearly describe a layer of thermally conductive material forming part of a multi-layer printed circuit board, as shown in Figure 1, while Paragraph 42 specifically notes that such a conductive layer can form part of a metalized film, as claimed in claims 5 and 6.

No new matter is introduced by any of the foregoing amendments.

It is submitted that the foregoing amendments must be sufficient to overcome the objection set out in Paragraph 8 of the final Office Action.

Entry of this Amendment After Appeal is respectfully requested on the grounds that it will not require extensive review by the Examiner, being confined to corrections needed to overcome minor inconsistencies in the claims, as noted for the first time in the final Office Action, but will simplify the issues which need to be decided in the pending appeal.

Respectfully submitted  
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